

ABSTRACT

The object of the present invention is to provide: a method for manufacturing a multilayer printed wiring board which enables the dielectric layers to have excellent thickness uniformity, the capacitor circuits to have high registration accuracy and the unnecessary dielectric layer is removed as large as possible; and a multilayer printed wiring board with an embedded capacitor circuit manufactured by the method. To achieve this object, a method is employed in which a multilayer printed wiring board with an embedded capacitor circuit is manufactured through: a first-conductive-metal-layer laminating step where a dielectric layer and a first conductive metal layer are provided on both sides of a core material having base electrode circuits; an top-electrode forming step where the first conductive metal layer(s) locating as outer layer(s) is(are) processed into top electrodes and the dielectric layer(s) in the area other than those of circuit portions is(are) exposed; a dielectric-layer removing step where the exposed dielectric layer(s), which is(are) in the area other than those of circuit portions, is(are) removed; a second-conductive-metal laminating step where the gaps among the top electrodes are filled in and an insulating layer and a second conductive metal layer are provided on the top electrodes; and an outer layer circuit forming

step where the second conductive metal layer(s) is(are) processed into outer layer circuits.